## 2SD0946A, 2SD0946B

## Silicon NPN epitaxial planar type darlington

## For low-frequency amplification

## Features

- Forward current transfer ratio $\mathrm{h}_{\mathrm{FE}}$ is designed high, which is appropriate to the driver circuit of motors and printer hammer.
- A shunt resistor is omitted from the driver.

Absolute Maximum Ratings $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$

| Parameter |  | Symbol | Rating | Unit |
| :--- | :---: | :---: | :---: | :---: |
| Collector-base voltage <br> (Emitter open) | 2SD0946A | $\mathrm{V}_{\text {CBO }}$ | 60 | V |
|  | 2SD0946B |  | 100 |  |
|  | 2SD0946A | $\mathrm{V}_{\text {CEO }}$ | 50 | V |
|  | 2SD0946B |  | 80 |  |
| Emitter-base voltage (Collector open) | $\mathrm{V}_{\text {EBO }}$ | 5 | V |  |
| Collector current | $\mathrm{I}_{\mathrm{C}}$ | 1 | A |  |
| Peak collector current | $\mathrm{I}_{\mathrm{CP}}$ | 1.5 | A |  |
| Collector power dissipation | $\mathrm{P}_{\mathrm{C}}$ | 1.2 | W |  |
| Junction temperature | $\mathrm{T}_{\mathrm{j}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |  |

- Package
- Code

TO-126B-A1

- Pin Name

1: Emitter
2: Collector
3: Base

- Internal Connection


Electrical Characteristics $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$

| Parameter |  | Symbol | Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Collector-base voltage (Emitter open) | 2SD0946A | $\mathrm{V}_{\text {CBo }}$ | $\mathrm{I}_{\mathrm{C}}=100 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{E}}=0$ | 60 |  |  | V |
|  | 2SD0946B |  |  | 100 |  |  |  |
| Collector-emitter voltage (Base open) | 2SD0946A | $\mathrm{V}_{\text {CEO }}$ | $\mathrm{I}_{\mathrm{C}}=1 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=0$ | 50 |  |  | V |
|  | 2SD0946B |  |  | 80 |  |  |  |
| Emitter-base voltage (Collector open) |  | $\mathrm{V}_{\text {Ebo }}$ | $\mathrm{I}_{\mathrm{E}}=100 \mu \mathrm{~A}, \mathrm{I}_{\mathrm{C}}=0$ | 5 |  |  | V |
| Collector-base cutoff current (Emitter open) |  | $\mathrm{I}_{\text {CBO }}$ | $\mathrm{V}_{\mathrm{CB}}=25 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=0$ |  |  | 0.1 | $\mu \mathrm{A}$ |
| Emitter-base cutoff current (Collector open) |  | $\mathrm{I}_{\text {EbO }}$ | $\mathrm{V}_{\mathrm{EB}}=4 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=0$ |  |  | 0.1 | $\mu \mathrm{A}$ |
| Forward current transfer ratio *1,2 |  | $\mathrm{h}_{\mathrm{FE}}$ | $\mathrm{V}_{\mathrm{CE}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=1 \mathrm{~A}$ | 4000 |  | 40000 | - |
| Collector-emitter saturation voltage ${ }^{* 1}$ |  | $\mathrm{V}_{\mathrm{CE} \text { (sat) }}$ | $\mathrm{I}_{\mathrm{C}}=1 \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=1 \mathrm{~mA}$ |  |  | 1.8 | V |
| Base-emitter saturation voltage *1 |  | $\mathrm{V}_{\mathrm{BE} \text { (sat) }}$ | $\mathrm{I}_{\mathrm{C}}=1 \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=1 \mathrm{~mA}$ |  |  | 2.2 | V |
| Transition frequency |  | $\mathrm{f}_{\mathrm{T}}$ | $\mathrm{V}_{\mathrm{CB}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=-50 \mathrm{~mA}, \mathrm{f}=200 \mathrm{MHz}$ |  | 150 |  | MHz |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *1: Pulse measurement
*2: Rank classification

| Rank | Q | R | S |
| :---: | :---: | :---: | :---: |
| $\mathrm{h}_{\mathrm{FE}}$ | 4000 to 10000 | 8000 to 20000 | 16000 to 40000 |







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